

Beyond the challenge

MEMS Qualification Procedure for Space Applications

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9th ESA Round Table on Micro and Nano Technologies





2

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1. Introduction

Outline

- Advantages of using MEMS for Space Applications
- Example of MEMS in Space Application
- Diversity of MEMS Devices
- 2. Criteria for MEMS Classification
 - Correlation with Test Plan Methodology
 - Levels of Failure Analysis
- 3. MEMS Qualification Process
 - Test Plan Flow
- 4. Conclusions and Future Work

MEMS for Space Applications





4

Examples of MEMS used in space



MEMS rate sensor in Cryosat-2^[1]



Digital pressure sensor used in ADM-Aeolus oxygen tank^[2]



^[1]http://www.esa.int/Our_Activities/Technology/MEMS_Rate_Sensor_on_CryoSat-2 ^[2]Technology Success Stories, ESA

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http://sci.esa.int/jwst/45694-nirspec-the-near-infrared-spectrograph/

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6

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7





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9

Diversity of MEMS Devices



Non-conventional materials

- Piezoelectric crystals
- Glass
- Polymers
- **Fabrication method**

Moving structures

Functionality

- Mechanical
- Optical

Different critical temperatures

Different mechanical sensitivities

Different functional sensitivities

Not possible to use the same qualification methods as for the EEE components

2. Criteria for MEMS Classification **uso**space MEMS were classified according to failure mechanisms 3 Criteria were chosen: Package Movement Electrical Hermetic packaging Packaged Non-**MEMS** Resistive hermetic device packaging Not **MFMS** Capacitive packaged device Impact Inductive **Motion** Moving structure MEMS No impact device motion Non moving structure

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Levels of Failure Analysis



- Packaging type
- Hermeticity level
- System integration: MEMS + electronic control

MEMS Specific Level

- Moving characteristics
 - moving/non-moving structure
 - impact motion
- Electrical principle:
 - resistive, capacitive or inductive

- Functional testing
 - Device specific
- Functional parameters' include:
- Working principle
- Active element type

Functional level

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System level

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MEMS Classification and Qualification Process — **Test Plan Methodology**



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3. MEMS Qualification Process Proposed Test Plan Flow Chart





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Proposed Test Plan Flow - Packaged related test methods





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Proposed Test Plan Flow - Hermeticity related test methods





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Proposed Test Plan Flow - Electrical related test methods





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Proposed Test Plan Flow – Movement related test methods





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Qualification Step-by-Step - Inspection Phase

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Inspection

Dimensions

Mass

19

Electrical Parameters* **External Visual Inspection** Non-destructive Internal Visual Inspection* Pin to pin isolation test Markings and Serialization

*Electrical Parameters

Depend on the MEMS device

*Non-destructive Internal Visual Inspection

- Method and procedure will depend
 - device dimensions + materials

Qualification Step-by-Step – Additional Inspection Phase





*Other spectroscopy methods

- For lower leak detection limit
- Used for small cavities (wafer level packaging, *e.g.*)

*PERA Periodic Excitation Response Analysis

 Condition depend on the characteristics of the MEMS device

Dynamic measurement

- Depends on the device's electrical characteristics

Qualification Step-by-Step – **Destructive** Tests





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Qualification Step-by-Step – *Environmental Tests*





 22
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Qualification Step-by-Step **— Endurance** Tests





Qualification Step-by-Step — Final Inspection





4. Conclusions and Future Work



Initial steps towards standard qualification method

Required feedback from industry

- Experience on materials sensitivity
- Experience on dynamic characterization of the devices

Next steps

- Validation of the qualification methodology:
 - 2 MEMS devices as case study
- Drafting of an ECSS Technical Memorandum



Thank you for your attention!

Questions?